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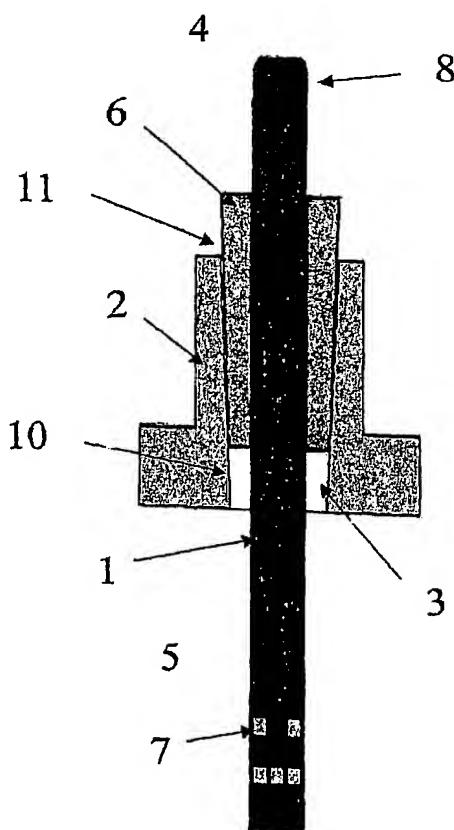
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(54) Title: A METHOD FOR FORMING A PRESSURE PROOF ASSEMBLY BETWEEN A COMPONENT AND HOUSE AND SUCH AN ASSEMBLY



(57) Abstract: The present invention relates to a method for pressure proof and tight assembling of a component to a wall of a house. The method is applicable for assembling components which are sensitive to high temperatures, e.g. for assembling an electronic pressure sensor in a house. According to the invention a component and the house is assembled via a sealing member, e.g. a sleeve, which is pressed into an opening between the component and the house until the yield point is exceeded for at least one of the component, the house and the sealing member.



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